

Environmental Management and Materials Information

Product Content Information for: MAX8211CPA+

Lead-Free Qualified	Yes
Moisture Sensitivity Level	L1

Package Code	Package Type	Body Size	Package Option	Pin Count
P8+1	PDIP	.300"	Standard	8

Qualified Assembler	Unit Weight	Flammability Meets UL-94 (V-0 Rating)
ATP	0.50459	Yes

Lead Frame Material	Lead Frame Components in Grams					
	Copper (Cu)	Iron (Fe)	Zinc (Zn)	Magnesium (Mg)	Nickel (Ni)	Chromium (Cr)
Copper C194	0.1791	0.0043	0.0002	ND	ND	ND

Die Attach Material	Die Attach Epoxy Components in Grams	
	Silver Filler (Ag)	Epoxy
Ablebond 84-1LMISR4	0.00249	0.001

Bond Wire ¹	Bond Wire in Grams
	Gold (Au)
Gold	0.0005

Mold Material	Mold Compound Components in Grams				
	Antimony (Sb203)	Bromine (Br)	Silica (SiO2)	Resin Type	Resin Weight
Sumitomo 6300H	0.0089	0.003	0.2044	OCN	0.0795

Lead Finish Plating	Plating in Grams		
	Tin (Sn)	NiPdAu	Gold (Au)
100% Tin	0.0132	N/A	N/A

Silicon Chip in Grams	Substrate Weight
0.008	N/A

Notes

1. Refer to product data sheet to confirm actual wire diameter.
2. 'ND' means None Detected, negligible amount present.

This part is qualified as lead-free.

Parts qualified as lead-free can be manufactured and supplied as lead-free, if and only if, the customer makes such requests to the Dallas Semiconductor/Maxim Business Units for approval. The navigation bar on the EMMI website contains information regarding the lead-free process (e.g. MSL's, Peak reflow Temperatures, JEDEC methods, frequently asked questions and answers, lead-free package tables, and status/qualification plans for particular package types qualified as lead-free or in the qualification process).

CALCULATIONS TABLE							
Substance Name	Percentage of Substance Mass (g)						
	Lead Frame Components	Die Attache Epoxy Components	Bond Wire Component	Mold Compound Components	Plating (Surface Finish) Components	Silicon Chip Components	All Components
Copper	97.5490	-	-	-	-	-	35.49416
Iron	2.34205	-	-	-	-	-	0.85218
Zinc	0.10893	-	-	-	-	-	0.03964
Magnesium	-	-	-	-	-	-	0.00000
Nickel	-	-	-	-	-	-	0.00000
Chromium	-	-	-	-	-	-	0.00000
Silver Filler	-	71.3467	-	-	-	-	0.49347
Epoxy	-	28.6533	-	-	-	-	0.19818
Gold	-	-	100.000	-	-	-	0.09909
Antimony trioxide	-	-	-	3.00879	-	-	1.76381
Bromine	-	-	-	1.01420	-	-	0.59454
Silica (SiO2)	-	-	-	69.1007	-	-	40.50814
Resin Weight	-	-	-	26.8762	-	-	15.75537
Tin	-	-	-	-	100.000	-	2.61599
Silicon	-	-	-	-	-	100.000	1.58545
NiPdAu	-	-	-	-	-	-	0.00000
Substrate	-	-	-	-	-	-	0.00000

This report was generated on 2006-06-20. For additional information, please visit the Maxim/Dallas Environmental Management and Materials Information website located at:

<http://www.maxim-ic.com/emmi>